

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JU-HYUNG LEE</td> <td>12/02/2013</td> </tr> <tr> <td>SOO-YEOL LEE</td> <td>11/20/2013</td> </tr> </tbody> </table>		Name	Execution Date	JU-HYUNG LEE	12/02/2013	SOO-YEOL LEE	11/20/2013		
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<table border="1"> <tr> <td>Name:</td> <td>SAMSUNG ELECTRONICS CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>129 SAMSUNG-RO, YEONGTONG-GU, SUWON-SI</td> </tr> <tr> <td>City:</td> <td>GYEONGGI-DO</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	SAMSUNG ELECTRONICS CO., LTD.	Street Address:	129 SAMSUNG-RO, YEONGTONG-GU, SUWON-SI	City:	GYEONGGI-DO	State/Country:	KOREA, REPUBLIC OF
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PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14096372</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14096372				
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CORRESPONDENCE DATA									
Fax Number:	(201)226-9246								
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>									
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Address Line 4:	PARAMUS, NEW JERSEY 07652								
ATTORNEY DOCKET NUMBER:	7200-1-015								

NAME OF SUBMITTER:	STEVE CHA
Signature:	/Steve Cha/
Date:	12/04/2013
<b>Total Attachments: 3</b> source=7200-1-015_Assignment#page1.tif source=7200-1-015_Assignment#page2.tif source=7200-1-015_Assignment#page3.tif	

## Assignment of Invention and Patent Application

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration,

- 1) Ju-hyung LEE of 409-1105 Jugong Apt., Byeoryang-dong, Gwacheon-si,  
Gyeonggi-do, Republic of Korea
- 2) Soo-yeol LEE of 304-304 Grandville, 111 Gumi-dong, Bundang-gu,  
Seongnam-si, Gyeonggi-do, Republic of Korea

(hereinafter **Assignor**) hereby sells, assigns, transfers, and sets over unto:

**SAMSUNG ELECTRONICS CO., LTD.** of  
**129 SAMSUNG-RO, YEONGTONG-GU, SUWON-SI, GYEONGGI-DO, 443-742**  
**REPUBLIC OF KOREA**  
&  
**INDUSTRY ACADEMIC COOPERATION FOUNDATION KYUNGHEE UNIVERSITY**  
of  
**1732 DEOGYEONG-DAERO, GIHEUNG-GU, YONGIN-SI, GYEONGGI-DO,**  
**REPUBLIC OF KOREA**

(hereinafter **Assignee**) the entire right, title and interest for the United States Of America as defined in 35 U.S.C. Section 261, in and to the invention entitled as:

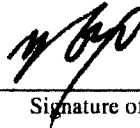
### **METHOD AND APPARATUS FOR ACQUIRING B1 MAGNETIC FIELD INFORMATION**

invented by **Assignor**; the application for United States patent therefor, invented by **Assignor**; any patent or reissues of any patent that may be granted thereon; and any applications which are continuations, continuation-in-part, substitutes, or divisions of said application. **Assignor** authorizes **Assignee** to enter the date of signature and/or Serial Number and Filing Date in the above. **Assignor** also authorizes and requests the Commissioner of Patents and Trademarks to issue any resulting patent(s) to the said **Assignee**, for its interests as **Assignee**, its successors, assigns and legal representatives. The undersigned agrees that the attorney of record in said application shall hereafter act on behalf of said **Assignee**; and **Assignor** further conveys to **Assignee** all priority rights resulting from the above-identified application for United States

Patent. **Assignor** agrees to execute all papers, give any required testimony and perform other lawful acts, as deemed essential by **Assignee** to perfect **Assignee's** interest in any resulting patent of the United States, and to acquire, hold, enforce, convey, and uphold the validity of said patent and reissues and extensions thereof, and **Assignee's** interest therein.

**SIGNED ON THE DATES(S) INDICATED BESIDE MY/OUR SIGNATURE(S):**

**Name of First Inventor:** Ju-hyung LEE



\_\_\_\_\_  
Signature of inventor

Dated: Dec. 2 . 2013

WITNESSED: \_\_\_\_\_

**Name of Second Inventor:** Soo-yeol LEE

\_\_\_\_\_  
Signature of inventor

Dated: \_\_\_\_\_

WITNESSED: \_\_\_\_\_

Patent. **Assignor** agrees to execute all papers, give any required testimony and perform other lawful acts, as deemed essential by **Assignee** to perfect **Assignee's** interest in any resulting patent of the United States, and to acquire, hold, enforce, convey, and uphold the validity of said patent and reissues and extensions thereof, and **Assignee's** interest therein.

**SIGNED ON THE DATES(S) INDICATED BESIDE MY/OUR SIGNATURE(S):**

**Name of First Inventor:** Ju-hyung LEE

\_\_\_\_\_  
Signature of inventor

Dated: \_\_\_\_\_

WITNESSED: \_\_\_\_\_

**Name of Second Inventor:** Soo-yeol LEE

*01/4/02*  
\_\_\_\_\_  
Signature of inventor

Dated: *Nov. 20, 2013*

WITNESSED: \_\_\_\_\_